



Material Content Data Sheet



Sales Product Name		IPD068N10N3 G		Issued		22. January 2018		
MA#		MA001662036						
Package		PG-TO252-3-313		Weight*		320.74 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.560	1.73	1.73	17336	17336
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		138	
	non noble metal	iron	7439-89-6	0.147	0.05		459	
	non noble metal	copper	7440-50-8	147.096	45.87	45.93	458612	459209
	non noble metal	aluminium	7429-90-5	4.096	1.28	1.28	12770	12770
wire	non noble metal	aluminium	7429-90-5	4.096	1.28	1.28	12770	12770
encapsulation	organic material	carbon black	1333-86-4	1.352	0.42		4214	
	plastics	epoxy resin	-	23.652	7.37		73741	
	inorganic material	silicondioxide	60676-86-0	110.150	34.34	42.13	343424	421379
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11661	11661
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4429	4440
solder	non noble metal	tin	7440-31-5	0.086	0.03		267	
	noble metal	silver	7440-22-4	0.107	0.03		333	
	non noble metal	lead	7439-92-1	4.085	1.27	1.33	12736	13336
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	5.98	5.99	59791	59869
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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